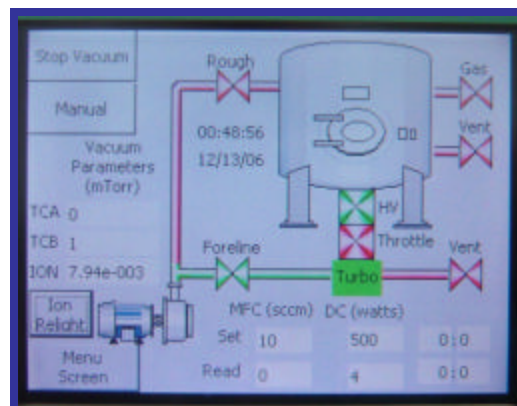




Hummer® BC-16 Series

ONE SYSTEM IN A FAMILY OF PLANAR MAGNETRON SPUTTERING SYSTEMS

THIN FILM DEPOSITION OF METALS AND INSULATORS



TOUCH-PANEL PROCESS CONTROL

Vacuum and Process Control all in one.
Functions are clearly displayed

QUARTZING
CV DOT MATRIX
FAILURE ANALYSIS
MATERIALS RESEARCH
SUPERCONDUCTOR RESEARCH
MICROELECTRONICS RESEARCH

BC Systems are available in sizes;
16", 20", 24" and 30" D-style chambers
(BC-20 chamber shown in photo)

The **HUMMER BC-16** sputter coater combines a high degree of process control and flexibility with ease of operation.

THIN FILM RESEARCH - FAILURE ANALYSIS - PRODUCTION SUPPORT

HUMMER BC-16

PLANAR MAGNETRON SOURCE

TARGET DIAMETER -
2" Standard,
Optional - 3" & 4" diameter
sources and Multiple sources
TARGET THICKNESS - 1/16 to
1/4" standard
TARGET MATERIALS - Metals
and / or insulators
SOURCE MOUNTING - Quick
coupling to chamber, shutters,
shields between sources as
necessary
POWER SUPPLY - 300 watts,
13.56 MHz. Standard
Optional - 600, 1000 watts RF
at 13.56 MHz.
1500 Watts Standard, Optional
- 2500 Watts DC, or various
combinations of supplies
COOLING WATER - .2 to 10
GPM required.
Optional - Recirculation sys-
tem
TARGET MOUNTING - Mechan-
ical clamp or magnetic keeper
depending upon requirement

STAGE FIXTURE

SIZE - 2", 3", 4", 6", 8" or 12"
MOTION -360° rotation standard.
Optional - Variable angle of inci-
dence to sputter source
COOLING - Optional
REVERSE SPUTTER/ETCH - Optional
HEATED - Optional to 1000° Celsius

SOURCE OPTIONS

Anatech USA offers alternatives for source configuration.
Contact our sales staff.

OVERALL SYSTEM

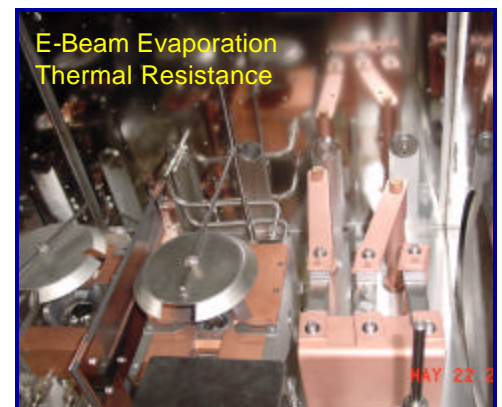
CHAMBER - 304 Stainless steel,
16" ID nominal, aluminum door,
4" Door view port, roughing,
High Vac pump and instrument
ports
CONTROL - Siemens S7-200
Series PLC control for each vac-
uum function and sputtering
source. Fully integrated with easy
"Touch-Panel" control pad for
diagnostic and setting system pa-
rameters
DESIGN - Floor mount cabinet
on casters with leveling pads
SAFETY INTERLOCKS - Water, door
and vacuum interlocks.
ELECTRICAL REQUIREMENTS -
40-75 AMP, 208-240 Volt,
50/60 HZ
SPUTTERING - Standard top down
sputtering. Optional - Sputter-up
or horizontal sputter
AUTOMATIC SEQUENCING -
Standard

IONIZATION SPECIES

GAS REQUIREMENTS - Argon
regulated from 5 to 20 PSI
OPERATING PRESSURE -
 2×10^{-3} to 5×10^{-2}
REACTIVE SPECIES - Optional

VACUUM SYSTEM

PUMPING - Roughing pump and
Turbo molecular pump - Standard
Optional - Cryo pump or Larger
pumps
VACUUM GAUGING - Convectron
gauges (2), Ion gauge (1).
Atmosphere to 1×10^{-8} TORR
VALVES - Electro-Pneumatic actuated
High Vacuum/Throttle valve be-
tween pump and chamber. Fore-line
and chamber roughing isolation
valves. Pneumatic air or nitrogen
(clean, dry) operating at 60-PSI.
GAS CONTROL - Mass Flow Controller
(1) 100 sccm. Optional - Gases (3)
maximum, for mixing and reactive
gas sputtering



CALL ANATECH USA TODAY TO DISCUSS YOUR APPLICATION

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